

CHUCK TABLE AND MANUFACTURING METHOD OF CHUCK TABLE

ABSTRACT

A chuck table includes a holding plate having a holding surface for holding the wafer under suction, and a frame body that supports the holding plate thereon and transmits a negative pressure or a positive pressure to the holding surface. The holding plate is formed such that a plurality of cleaved portions are included through cleavage of the holding plate into a plurality of blocks along a plurality of modified layers formed by applying a laser beam of a wavelength, which has transmissivity through the holding plate, with a focal point thereof positioned inside the holding plate, and the negative pressure or the positive pressure is transmitted from the cleaved portions to the holding surface. A grinding machine and a manufacturing method of the chuck table for holding the wafer are also disclosed.

[FIG. 3A]